

This Page Is Inserted by IFW Operations  
and is not a part of the Official Record

## **BEST AVAILABLE IMAGES**

Defective images within this document are accurate representations of the original documents submitted by the applicant.

Defects in the images may include (but are not limited to):

- BLACK BORDERS
- TEXT CUT OFF AT TOP, BOTTOM OR SIDES
- FADED TEXT
- ILLEGIBLE TEXT
- SKEWED/SLANTED IMAGES
- COLORED PHOTOS
- BLACK OR VERY BLACK AND WHITE DARK PHOTOS
- GRAY SCALE DOCUMENTS

**IMAGES ARE BEST AVAILABLE COPY.**

**As rescanning documents *will not* correct images,  
please do not report the images to the  
Image Problem Mailbox.**

**IN THE UNITED STATES PATENT AND TRADEMARK OFFICE**

APPLICANT : Gambino et al.  
SERIAL NO : Division of Prior Application S/N 10/193,497  
ART UNIT : 2652 (for Prior Application)  
FILING DATE : herewith  
ATT'Y NO. : YOR919930093US3  
EXAMINER : Craig A. Renner (for Prior Application)  
TITLE : Magnetoiresistive Sensor With Magnetostatic Coupling of  
Magnetic Regions

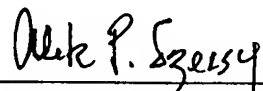
Commissioner of Patents  
PO Box 1450  
Alexandria, VA 22313

**INFORMATION DISCLOSURE STATEMENT**

Sir:

In accord with 37 C.F.R. 1.97-1.98, appended please find a listing of references that may be relevant to the above-referenced application. The listing of references is not a representation that a search has been made, that better references than listed do not exist, or that other references are not applicable. Moreover, this listing does not constitute any admission by applicants or applicants' attorney that the information provided herein is necessarily prior art to applicants' invention.

Respectfully submitted,

  
Alek P. Szecsy (Reg. No. 37,949)

83 Spruce Ridge Drive  
Fishkill, NY 12524  
845-838-9251 (voice/facsimile)

15 April 2004

LIST OF REFERENCES CITED BY APPLICANT  
(Use several sheets if necessary)

ATTY. DOCKET NO.

Y02919930093US2

SERIAL NO.

APPLICANT: Richard J. Gambino et al.

FILING DATE:

herewith

GROUP:

U.S. PATENT DOCUMENT

Examiner Initial	Document Number	Date	Name	Class	Sub-Class	Filing Date
AA	5,159,513	10/92	Dieny et al.	360	113	02/08/91
AB	5,134,533	07/92	Friedrich et al.	360	113	02/28/92
AC	5,119,025	06/92	Smith et al.	324	252	07/30/91
AD	5,038,131	08/91	Olk et al.	338	32 R	02/23/90
AE	4,987,094	01/91	Colas et al.	437	81	06/02/89
AF	3,879,760	04/75	Jean-Pierre Lazzari	360	113	02/22/74
AG	3,256,483	06/66	Kent D. Broadbent	324	65	06/15/61
AH	5,155,643	10/92	Jones, Jr. et al.	360	113	10/30/90
AI	5,085,935	02/92	Michael L. Mallary	428	336	06/02/89
AJ	5,084,794	01/92	Neil Smith	360	113	03/29/90
AK	4,686,472	08/87	Van Ooljen et al.	324	252	02/10/86

FOREIGN PATENT DOCUMENTS

	DOCUMENT NUMBER	DATE	COUNTRY	CLASS	SUB-CLASS	TRANSLATION Y/N
AL	JP 04-1907	01/92	Japan	G11B	5/39	Abstract
AM	JP 04-26160	01/92	Japan	H01L	29/06	Abstract
AN						
AO						
AP						

OTHER REFERENCES (Including author, title, date, pertinent pages, etc.)

AR	S. S. P. Parkin et al., "Oscillations in Exchange Coupling and Magnetoresistance in Metallic Superlattice Structures: Co/Ru, Co/Cr, and Fe/Cr", Ph. Rev. Let., Vol. 64, No. 19, pp. 2304-07, 7 May 1990.
AS	W. P. Pratt, Jr. et al., "Perpendicular Giant Magnetoresistances of Ag/Co Multilayers", Ph. Rev. Let., Vol. 66, No. 23, pp. 3060-63, 10 June 1991.
AT	J. Q. Xiao et al., "Giant Magnetoresistance in Nonmultilayer Magnetic Systems", Ph. Rev. Let., Vol. 68, No. 25, pp. 3749-52, 22 June 1992.

EXAMINER

DATE CONSIDERED

\*EXAMINER: Initial if reference considered, whether or not citation is in conformance with MPEP 609; Draw line through citation if not in conformance and not considered. Include copy of this form with next communication to applicant.

LIST OF REFERENCES, CITED BY APPLICANT  
(Use several sheets if necessary)

ATTY. DOCKET NO.

Y62919930093US3

SERIAL NO.

APPLICANT: Richard J. Gambino et al.

FILING DATE:

herewith

GROUP:

U.S. PATENT DOCUMENT

Examiner Initial	Document Number	Date	Name	Class	Sub-Class	Filing Date
CA						
CB						
CC						
CD						
CE						
CF						
CG						
CH						
CI						
CJ						
CK						

FOREIGN PATENT DOCUMENTS

	DOCUMENT NUMBER	DATE	COUNTRY	CLASS	SUB-CLASS	TRANSLATION Y/N
CL						
CM						
CN						
CO						
CP						

OTHER REFERENCES (Including author, title, date, pertinent pages, etc.)

CR	K. Y. Ahn, "BUBBLE DEVICE FABRICATION", IBM Technical Disclosure Bulletin, Vol. 18, No. 12, May 1976, page 4204.
CS	K. Y. Ahn et al., "FABRICATION OF BUBBLE DOMAIN CONTIGUOUS DISK DEVICES", IBM Technical Disclosure Bulletin, Vol. 22, No. 7, December 1979, pp. 2991-2992.
CT	

EXAMINER

DATE CONSIDERED

\*EXAMINER: Initial if reference considered, whether or not citation is in conformance with MPEP 609; Draw line through citation if not in conformance and not considered. Include copy of this form with next communication to applicant.

LIST OF REFERENCES CITED BY APPLICANT  
(Use several sheets if necessary)

ATTY. DOCKET NO.  
YOR919930093U53

SERIAL NO.

APPLICANT: Richard J. Gambino et al.

FILING DATE:  
here with

GROUP:

U.S. PATENT DOCUMENT

Examiner Initial	Document Number	Date	Name	Class	Sub-Class	Filing Date
BA	3,887,944	06/75	Bajorek et al.	360	113	06/29/73
BB						
BC						
BD						
BE						
BF						
BG						
BH						
BI						
BJ						
BK						

FOREIGN PATENT DOCUMENTS

	DOCUMENT NUMBER	DATE	COUNTRY	CLASS	SUB-CLASS	TRANSLATION Y/N
BL						
BM						
BN						
BO						
BP						

OTHER REFERENCES (Including author, title, date, pertinent pages, etc.)

BR	B. Voigtlander et al., "Epitaxial growth of Fe on Au(111): a scanning tunneling microscopy investigation", Surface Science Letters, Vol. 255, (1991), pp. L529-L535.
BS	J. A. Strosio et al., "Microscopic aspects of the initial growth of the metastable fcc iron on Au(111)", J. Vac. Sci. Technol. A 10(4), Jul/Aug 1992, pp. 1981-1985.
BT	W. W. Chow et al., "ASPECT RATIO OF MAGNETORESISTIVE DETECTOR STRIPES", IBM Technical Disclosure Bulletin, Vol. 24, No. 3, Page 1481, August 1981.

EXAMINER

DATE CONSIDERED

\*EXAMINER: Initial if reference considered, whether or not citation is in conformance with MPEP 609; Draw line through citation if not in conformance and not considered. Include copy of this form with next communication to applicant.